



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLF11251LD	Issued	12. April 2021
MA#	MA005401845		
Package	PG-TSON-10-2	Weight*	31.95 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.606	5.03	5.03	50256	50256
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		104	
	non noble metal	zinc	7440-66-6	0.013	0.04		415	
	non noble metal	iron	7439-89-6	0.265	0.83		8303	
	non noble metal	copper	7440-50-8	10.773	33.72	34.60	337154	345976
wire	non noble metal	copper	7440-50-8	0.086	0.27	0.27	2698	2698
encapsulation	organic material	carbon black	1333-86-4	0.036	0.11		1134	
	plastics	epoxy resin	-	1.866	5.84		58393	
	inorganic material	silicondioxide	60676-86-0	16.212	50.74	56.69	507396	566923
leadfinish	non noble metal	tin	7440-31-5	0.370	1.16	1.16	11583	11583
plating	noble metal	silver	7440-22-4	0.064	0.20	0.20	2011	2011
glue	plastics	epoxy resin	-	0.164	0.51		5138	
	noble metal	silver	7440-22-4	0.493	1.54	2.05	15415	20553
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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